

FY2025 Q2 Financial Results Briefing

November 6, 2025



MEIKO ELECTRONICS CO., LTD.
(Securities Identification Code: 6787)

FY2025 Q2 Financial Results - Consolidated

(billion yen)

		FY2024		FY2025				Y-on-Y		Q-on-Q	
		H1 result	%	Q1 result	Q2 result	H1 result	%	Diff.	%	Diff.	%
Net sales	PCB	81.8		42.7	49.3	92.0		10.2	12.5%	6.6	15.5%
	Electronic Equipment	16.4		10.4	9.1	19.5		3.1	18.9%	-1.3	-12.5%
		98.2		53.1	58.4	111.5		13.3	13.6%	5.3	10.0%
Operating income	PCB	8.6	10.5%	4.8	5.2	10.0	10.9%	1.4	16.3%	0.4	8.3%
	Electronic Equipment	0.7	4.3%	0.8	0.6	1.4	7.2%	0.7	100.0%	-0.2	-25.0%
		9.3	9.5%	5.6	5.8	11.4	10.2%	2.1	22.9%	0.2	3.6%
Ordinary income		8.0	8.2%	4.9	6.5	11.4	10.2%	3.4	41.9%	1.6	32.7%
Net income		6.3	6.5%	3.8	5.6	9.4	8.4%	3.1	48.3%	1.8	47.4%
Average FX rate (JPY/USD)		152.46		143.72	148.35	146.04					

FY2025 Result - Net Sales by Product Application

(billion yen)

	FY2024	FY2025			Y-on-Y		Q-on-Q	
	H1 results	Q1 result	Q2 results	H1 results	Diff	%	Diff	%
Automotive	45.4	22.1	24.8	46.9	1.5	3.3%	2.7	12.2%
Smartphones Tablets	12.1	6.0	7.2	13.2	1.1	9.1%	1.2	20.0%
Telecommunications	8.9	4.8	7.0	11.8	2.9	32.6%	2.2	45.8%
Package	0.7	0.4	0.7	1.1	0.4	57.1%	0.3	75.0%
Module	6.3	3.6	3.8	7.4	1.1	17.5%	0.2	5.6%
Amusement/Smart Appliances /Industrial Equipment /Other Substrates	8.4	5.8	5.8	11.6	3.2	38.1%	0.0	0.0%
Electronic Equipment	EMS	8.5	4.5	4.2	8.7	0.2	-0.3	-6.7%
	ODM	7.9	5.9	4.9	10.8	2.9	-1.0	-16.9%
Electronic Equipment	16.4	10.4	9.1	19.5	3.1	18.9%	-1.3	-12.5%
Total	98.2	53.1	58.4	111.5	13.3	13.6%	5.3	10.0%

FY2025 Result - Net Sales by Product Specification

(billion yen)

		FY2024	FY2025			Y-on-Y		Q-on-Q	
		H1 results	Q1 results	Q2 results	H1 results	Diff	%	Diff	%
	4-layer board or lower	22.1	10.2	10.9	21.1	-1.0	-4.5%	0.7	6.9%
	6-layer board or higher	16.6	8.4	9.1	17.5	0.9	5.4%	0.7	8.3%
	MLB	38.7	18.6	20.0	38.6	-0.1	-0.3%	1.4	7.5%
	8-layer board or lower	25.0	11.4	15.0	26.4	1.4	5.6%	3.6	31.6%
	10-layer board or higher	14.7	11.3	12.0	23.3	8.6	58.5%	0.7	6.2%
	HDI	39.7	22.7	27.0	49.7	10.0	25.2%	4.3	18.9%
Package		0.7	0.4	0.7	1.1	0.4	57.1%	0.3	75.0%
Flexible/High Dissipation /Other Substrates		2.7	1.0	1.6	2.6	-0.1	-3.7%	0.6	60.0%
	EMS	8.5	4.5	4.2	8.7	0.2	2.4%	-0.3	-6.7%
	ODM	7.9	5.9	4.9	10.8	2.9	36.7%	-1.0	-16.9%
	Electronic Equipment	16.4	10.4	9.1	19.5	3.1	18.9%	-1.3	-12.5%
Total		98.2	53.1	58.4	111.5	13.3	13.6%	5.3	10.0%

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